

P-Channel Enhancement Mode Field Effect Transistor

Features

$V_{DS} (V) = -20V$,

$I_D = -2A$ ($V_{GS} = -4.5V$)

$R_{DS(ON)} < 120m\Omega$ @ $V_{GS} = -4.5V$

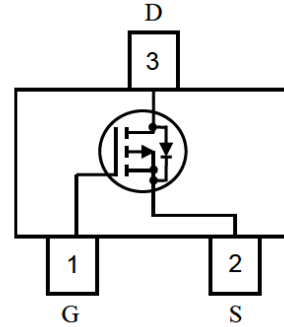
$R_{DS(ON)} < 150m\Omega$ @ $V_{GS} = -2.5V$

SOT23 Package

General Description

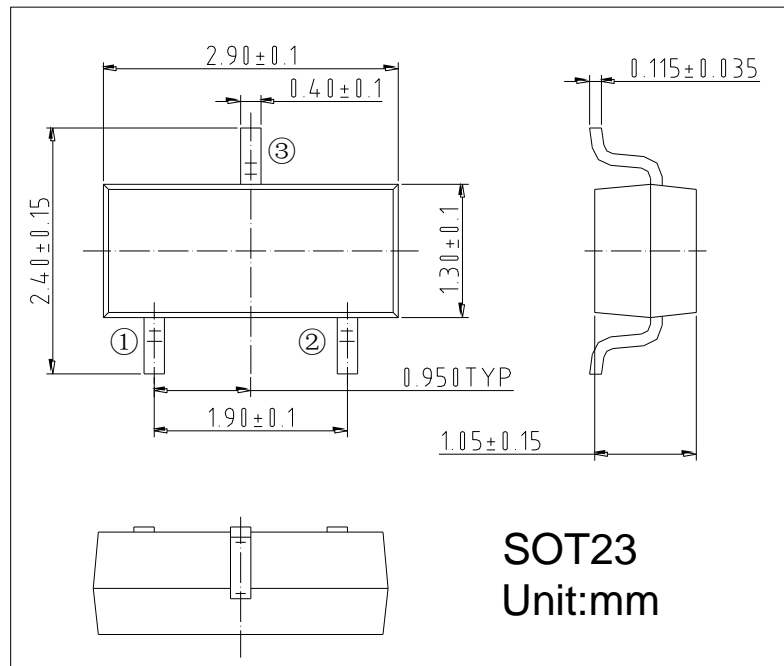
These P-Channel enhancement mode field effect transistors are produced using high cell density, DMOS technology.

Pin Configurations



MARKING:A1SHB

Package Information



Absolute Maximum Ratings @ $T_A = 25^\circ C$ unless otherwise noted

Parameter	Symbol	Ratings	Unit
Drain-Source Voltage	V_{DSS}	-20	V
Gate-Source Voltage	V_{GSS}	± 12	V
Drain Current (Continuous)	I_D	-2	A

	$T_A=70^{\circ}\text{C}$		-1.8	
Drain Current (Pulse)		I_{DM}	-7	A
Power Dissipation	$T_A=25^{\circ}\text{C}$	P_D	1	W
Operating Temperature/ Storage Temperature		T_{J}/T_{STG}	-55~150	$^{\circ}\text{C}$

● **Electrical Characteristics** @ $T_A=25^{\circ}\text{C}$ unless otherwise noted

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
ON/OFF CHARACTERISTICS						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_D = -250\mu A$	-20	--	--	V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = -20V, V_{GS} = 0V$	--	--	-1	μA
Gate Threshold Voltage	$V_{GS(th)}$	$V_{GS} = V_{DS}, I_{DS} = -250\mu A$	-0.4	-0.65	-0.9	V
Gate Leakage Current	I_{GSS}	$V_{GS} = \pm 12V, V_{DS} = 0V$	--	--	± 100	nA
Drain-Source On-state Resistance	$R_{DS(on)}$	$V_{GS} = -4.5V, I_D = -2A$	--	88	120	m Ω
		$V_{GS} = -2.5V, I_D = -1A$	--	120	150	m Ω
Forward Transconductance	g_{FS}	$V_{DS} = -5V, I_D = -2.8A$	--	6.5	--	S
Diode Forward Voltage	V_{SD}	$I_{SD} = -1.6A, V_{GS} = 0V$	--	-0.86	-1.1	V
Max Diode Forward Voltage	I_S		--	--	-1.6	A
Switching CHARACTERISTICS						
Total Gate Charge	Q_g	$V_{DS} = -6V, I_D = -2.8A$ $V_{GS} = -4.5V$	--	4.9	--	nC
Gate-Source Charge	Q_{gs}		--	0.62	--	nC
Gate-Drain Charge	Q_{gd}		--	1.07	--	nC
Turn-on Delay Time	$t_{d(on)}$	$V_{DD} = -6V, R_L = 6\Omega$ $I_D = -1A, V_{GEN} = -4.5V$ $R_G = 6\Omega$	--	10.1	--	ns
Turn-on Rise Time	t_r		--	4.76	--	ns
Turn-off Delay Time	$t_{d(off)}$		--	84.1	--	ns
Turn-off Fall Time	t_f		--	25.2	--	ns
Dynamic CHARACTERISTICS						
Input Capacitance	C_{iss}	$V_{GS} = 0V, V_{DS} = -6V, f = 1.0MHz$	--	472	--	pF
Output Capacitance	C_{oss}		--	71	--	pF
Reverse Transfer Capacitance	C_{rss}		--	51	--	pF

Notes:

1. Pulse width limited by maximum junction temperature.
2. Pulse test: $PW \leq 300\mu s$, duty cycle $\leq 2\%$.
3. For design AID only, not subject to production testing.
4. Switching time is essentially independent of operating temperature.

Typical Performance Characteristics

Fig.1 Output Characteristic

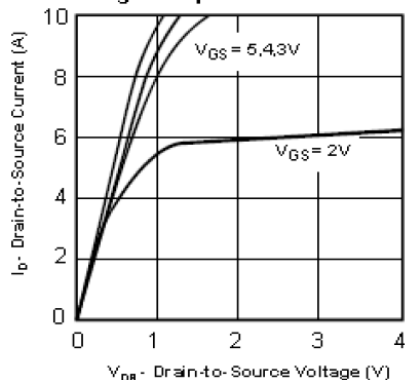


Fig.2 Transfer Characteristics

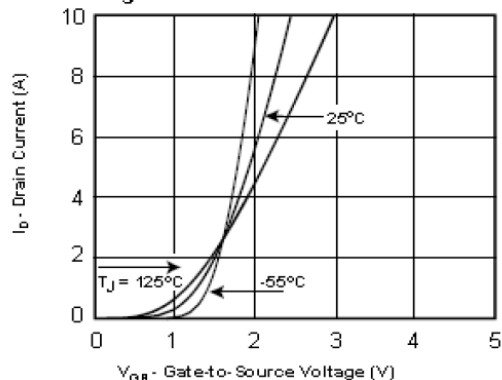


Fig.3 On-Resistance Variation with Temperature

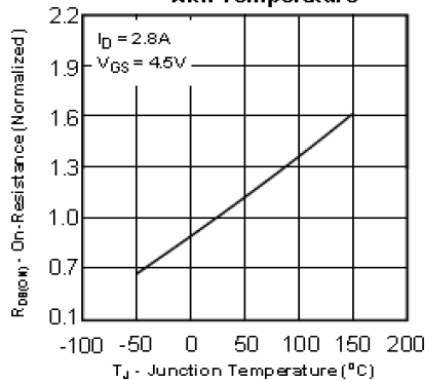


Fig.4 Body Diode Forward Voltage Variation with Source Current

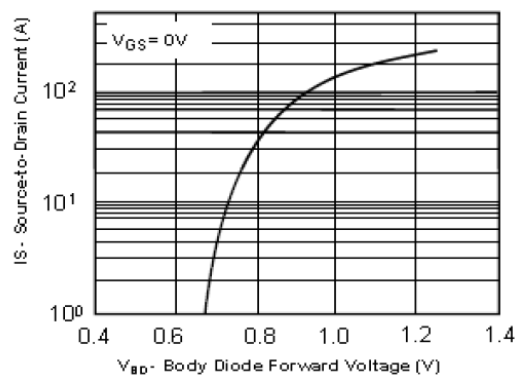


Fig.5 Gate Threshold Variation with Temperature

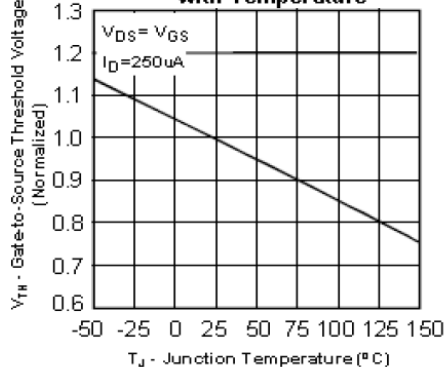


Fig.6 Capacitance

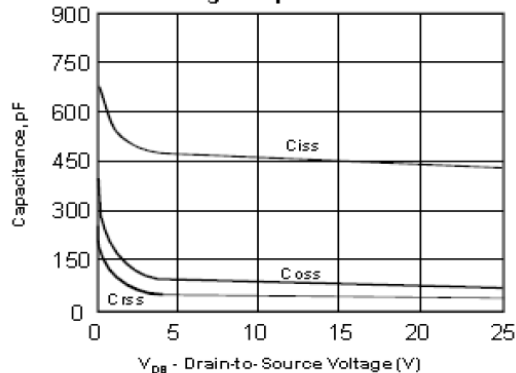


Fig. 7 Gate Charge Waveform

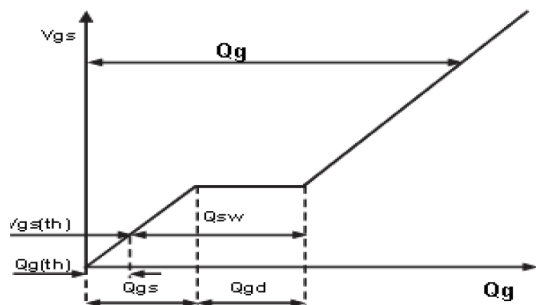


Fig. 8 Gate Charge

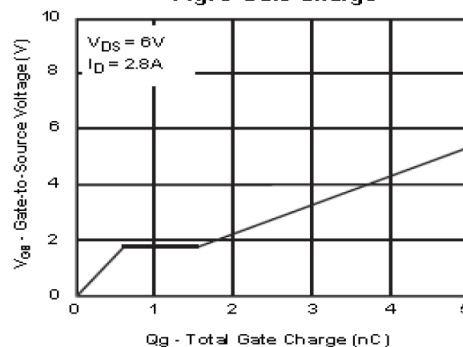


Fig. 9 Maximum Safe Operating Area

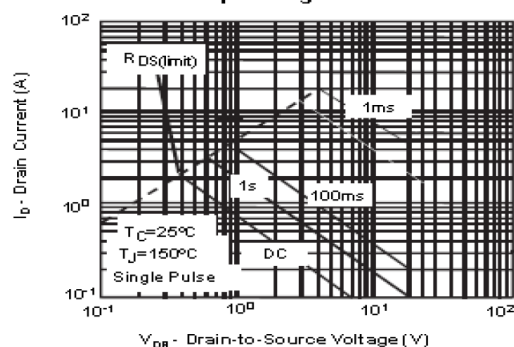


Fig. 10 Normalized Thermal Transient Impedance Curve

